

**PCB Stack-up and Technical Requirements**

**Our minimum specifications are as follow:**

Number of layers:                                          **2 layers**

Minimum line width (<=):                           **8 mils**

Minimum line spacing/gap (<=):              **8 mils**

Minimum Annular Ring (<=):                     **8 mils**

Minimum mechanical hole size (<=):     **0,3mm**

Surface finish:                                                **HASL**

Electrical Test: **100% Electrical Test (E-Test)**

Substrate type: **FR-4**

**Stencil:**

The global fiducials for the stencil are indicated on the **top-left, bottom-left and bottom-right** corners of the stencil files. The fiducials shall not be considered as openings for solder paste. The stencil shall be made in **stainless steel** and **laser cut**. The fiducials shall be produced in order to ensure good alignment and many production cycles. **Stencil thickness is 5mils.**

Please quote 1 stencil, **FRAMED using the standard 29” frame.**

**PCB Stack-up and files:**

|  |  |  |
| --- | --- | --- |
| Layer name | Thickness (mm) | File extension |
| Silkscreen Top (White) | - | \*.GTL |
| Soldermask Top (Red) | - | \*.GTS |
| Copper Top | 0,036 | \*.GTL |
| Dielectric | 1,5 | - |
| Copper Bottom | 0,036 | \*.GBL |
| Soldermask Bottom (Red) | - | \*.GBS |
| Silkscreen Bottom (White) | - | \*.GBO |
|  |  |  |
| Total thickness | 1,572 |  |
|  |  |  |
| File type |  | File Extension |
| Stencil top |  | \*.GTP |
| Board outline |  | \*.GM1 |
| Drill information (2.5 / Leading zero suppression) | | \*.TXT |
| (All vias are 100% pass through) |  |  |